Implementing a Fast 3-D Vision with Multiple TMS320C31 DSPs

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ESIEE, Paris
September 1996
SPRA331
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Implementing a Fast 3-D Vision Sensor with Multiple TMS320C31 DSPs

Abstract

The stereovision process determines the distances of objects by acquiring two images in different positions and studying the difference in locations of the corresponding stereo points. Various techniques have been developed to infer 3-D information from a set of brightness images. One technique, called passive stereovision, is appealing because of its ranging applications and especially because of its ability to work in various illumination conditions and with a large depth range (HOR 91).

This application report describes an automatic stereovision process with mobile robot guidance and autonomous vehicle navigation. Because the performance of this system requires high-speed response, the stereovision algorithms are implemented on specialized architecture that includes three Texas Instruments (TI™) TMS320C31 digital signal processors (DSPs). The 150/40-vision system from Imaging Technology has been chosen to implement the stereovision algorithms because it is a modular system that allows the parallelism of many image treatments.

Experimental results are presented at the end of this paper.

This document was part of the first European DSP Education and Research Conference that took place September 26 and 27, 1996 in Paris. For information on how TI encourages students from around the world to find innovative ways to use DSPs, see TI’s World Wide Web site at www.ti.com.
Product Support on the World Wide Web

Our World Wide Web site at www.ti.com contains the most up to date product information, revisions, and additions. Users registering with TI&ME can build custom information pages and receive new product updates automatically via email.
Stereovision Process

In general, the stereovision process consists of three steps:

- Feature extraction in right and left images
- Feature matching
- Calculation of the 3-D map

To reduce computation time and simplify the stereovision algorithms, we chose a special configuration. The two cameras have parallel optical axis and the \( i \)th scanline of the right and left CCDs is in the exact extension of each other. Given this configuration, the epipolar lines are confused with the scanlines of the CCDs. Consequently, the stereovision algorithms can be processed line by line.

The first step of our stereovision system is based on a new concept that we call declivity. Three-dimensional reconstruction is based on the detection and matching of characteristic declivities. In an image line, they are detected using an automatic threshold [MIC 94]. Furthermore, to be matched, this primitive is characterized by its position and the photometric characteristic of its neighborhood.

To match declivities, the second step of the system is based on a new matching algorithm, which uses dynamic programming method [BEN 96]. The algorithm parameters depend on those calculated on the detection phase of declivities.

Once the matching declivities are found, the 3-D information is deduced using disparity values and the depth map is completed by interpolation.
System

The system uses the 150/40 VME vision system from Imaging Technology. This modular system allows general-purpose image treatment and specific processes depending on the chosen configuration. It is composed of motherboards at the VME format on which can be plugged specific modules.

Our configuration is composed of two motherboards: an Advanced Image Manager (IMA) and a Computational Module Controller (CMC), one of which is a plugged module. (See Figure 2.) The motherboards include the following modules:

- Color Acquisition Module (AM_CLR) plugged into the IMA
- Pseudo Color Display Module (DM-PC) plugged into the IMA
- Three Programmable Accelerator Computational Modules (CM_PA) based on the TI floating point TMS320C31 DSP; one plus into the IMA and the others plug into the CMC

Advanced Image Manager

The IMA contains four Megabytes of reconfigurable image memory, a cross-port switch for data routing, and three supports for plug-in modules.

Memory is organized into four frames of 1K x 1K x 8 bits. Each frame is provided with two asynchronous 8-bit video ports: one for input and the other for output. In our case, we use only three frames: one for display and two for acquisition from cameras.

The cross-port switch is a specific circuit that allows configuring connections between the six 8 bit inputs and the six 8 bit outputs of IMA, and inputs and outputs of IMA modules.

Computational Module Controller

As for the IMA, it provides supports for three plug-in computational modules and a cross-port switch to configure data communication for modules.

The cross-port switch allows configuring video connections with external boards: six 8 bit inputs and three 8-bit outputs as well as video connections between modules of the CMC.

The CMC also provides local connections between serial ports of computational modules.
Programmable Accelerator Computational Module

The CM_PA is based on the floating point TMS320C31 DSP (see Figure 1.) The TMS320C31 has an addressing space of 24 bits, a 32 bits data width, two 2K x 32 bits single cycle RAM, a 64 x 32 bits instruction cache, a single cycle floating point multiplier, a single cycle ALU, two address generators, and a DMA controller.

The DSP addresses four different types of external memory:

- **Program memory**
  128 x 32 bits of zero wait state static RAM for program store, extended stack, coefficient storage, and general purpose memory.

- **Dual port RAM**
  4K x 16-bit memory shared by the DSP and the CPU host allows communications without halting the DSP. In our process, it is used only during initialization when the host loads program code and configures the CM_PA.

- **Image memory:**
  1M x 32 bits addressable by the DSP, by the VME host, and by the video data bus. Image memory cannot be accessed simultaneously by a different process. Access time is 1 wait state for access in the same row of 1K wide and 3 wait states in different rows.

- **Flash EEPROM boot memory**
  256K x 32 bits that allows the TMS320C31 to boot itself. If a system is composed only of IMAs with one CM_PA each, flash EEPROM memory allows it to be independent of the host. This memory is not used in our 3-D vision sensor application.

External Communication Devices

The following external communication devices are included:

- **Dual port RAM**

- **One 16-bit video input port** used to connect to the video bus. This port is not separable in two 8-bit ports but the use of only 8 bits is possible. The same characteristics are available for video output.

- **One serial link**
Figure 1. CM_PA Block Diagram

Figure 2 shows the general scheme of the 3-D vision sensor system.
The host at the initialization configures all of the system. In our case, the CM_PA of the IMA is the server unit. During the computation process, it controls the cross-port switch and the modules of the IMA.
The Imaging Technology vision system includes software utilities and libraries used to configure boards and modules and manage computation of CM_PAs. The C program language is used both for the host and DSP. Debugging the DSP program is possible only for the CM_PA of IMA when it is not a server. To develop the 3-D sensor programs, the serial port of CM_PAs controls data flows and computations.
Tasks Allocation

To take advantage of the three DSPs, the stereovision process is separated into tasks distributed as follows (see Figure 3):

- The two DSPs on the CMC are allocated for right and left image segmentation.
- The DSP on the IMA (which is the server) matches characteristic elements issued from DSPs of the CMC and manages acquisition and data transfer.

Figure 3. Tasks Allocation and Data Transfer

Data communications are made via the video buses. All data transferred by video buses must have the same image format, here imposed by the acquisition, which are 512 x 512 x 8 bits. The data transfer step is time critical due to the amount of data communications.
During a loop (excluding the first one since it is particular), right and left images are acquired synchronously in the IMA frame memory during the matching of characteristic elements issued of the previous stereo image pair. (See Figure 4.) This implies no time penalty because the acquisition in IMA memory frame is managed by the IMA board without halting the DSP.

Next, images are transferred from the IMA memory frame to the image memories of CM_PAs of the CMC. The DSPs must wait for the end of image loading before extracting declivities. Characteristic elements are then converted into an image format, loaded in image memory, and dumped to the video bus connected to the IMA board.

To get back characteristic elements, the DSP of the IMA connects its entry port to the video bus linked with one of the DSPs of the CMC and acquires the characteristic element image. Then it connects its entry port to the video bus linked with the other DSP of the CMC and acquires the other characteristic elements.

Characteristic element images are converted and loaded in DSP RAM (which is a one wait state memory) and matched to calculate the 3-D map. Results are then converted into an image format, written in DSP image memory, and dumped to the display.

This process is looped in each DSP as shown in Figure 4 and Figure 5.
## Figure 4. Chronogram

<table>
<thead>
<tr>
<th>IMA</th>
<th>DSP of IMA</th>
<th>DSP1 of CMC</th>
<th>DSP2 of CMC</th>
</tr>
</thead>
<tbody>
<tr>
<td>Right and left image acquisition in frame memory</td>
<td>Acquisition of right image from video bus</td>
<td>Acquisition of right image from video bus</td>
<td>Acquisition of left image from video bus</td>
</tr>
<tr>
<td>Dump acquisition frame memories to the video buses</td>
<td>Decivities extraction</td>
<td>Decivities extraction</td>
<td>Decivities extraction</td>
</tr>
<tr>
<td>Dump acquisition frame memories to the video buses</td>
<td>Dump decivities to video bus</td>
<td>Dump decivities to video bus</td>
<td></td>
</tr>
<tr>
<td>Right and left image acquisition in frame memory</td>
<td>Matching of decivities</td>
<td>Acquisition of right image from video bus</td>
<td>Acquisition of left image from video bus</td>
</tr>
<tr>
<td>Dump depth map to video bus</td>
<td>Decivities extraction</td>
<td>Decivities extraction</td>
<td></td>
</tr>
<tr>
<td>Acquisition of right decivities from video bus</td>
<td>Dump decivities to video bus</td>
<td>Dump decivities to video bus</td>
<td></td>
</tr>
<tr>
<td>Acquisition of left decivities from video bus</td>
<td>Dump decivities to video bus</td>
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<td></td>
<td>Dump decivities to video bus</td>
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</table>

Implementing a Fast 3-D Vision with Multiple TMS320C31 DSPs
The serial link is dedicated to the synchronization task. Before the beginning of the stereo process, the DSPs must wait for the end of the load of the program code in each DSP. For this, the IMA DSP emits a zero on the serial link to the first CMC DSP. Next, it emits the received number incremented by one until a three is emitted and received. In case of erroneous transmission (reception of a number different of 0, 1, 2, or 3) the process comes back to the beginning by emitting a zero.

For synchronization, the same process is used for all of the various tasks, acquisition, segmentation, and matching. Synchronization words corresponding at the beginning or at the end of each task are transmitted by the serial link.
Figure 5. Synchronization by serial link
Results

The sensor was tested with indoor and outdoor scenes. The rate of the sensor is calculated from 200 successive processes on images, which have a format of 512 x 512 x 8 bits. The computation times comprise between 1 and 1.5 seconds, depending on the scene complexity. The following result corresponds to an indoor scene involving a chair in front of a white board. (See Figure 6, Figure 7, and Figure 8.)

*Figure 6. Left Image*
Figure 7. Right Image
In the resulting depth map, dark pixels mean far points and white pixels mean near points.

The computation time for this scene is about 1.1 seconds. This allows time to consider specific applications, such as robot guidance.
Summary

Results obtained with the 150/40-vision system from Imaging Technology show that the Texas Instruments TMS320C31 DSPs are well suited for our 3-D vision sensor algorithms. We hope that new DSP generations, such as the Texas Instruments TMS320C80 will significantly reduce processing time. A system with fast shared memory will exchange data (characteristic elements) without needing any image format conversion. Moreover, the treatments can be made line by line allowing a high parallelism level.

References

